

## **Interview with MRSI Systems: MRSI will build a new DEMO Center in Shenzhen China to support the rapid development of China's photonics industry**

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Abstract: In this year's Laser World of Photonics China(Shanghai), MRSI Systems continues to bring the most advanced 1.5 micron high-speed, high-precision, ultra-flexible automatic die bonder to provide on-site demonstration for domestic device manufacturers. The MRSI-H series die bonders are the industry's proven solution for high-precision photonic production devices.

Laser World of Photonics China was held in Shanghai New International Expo Center from March 17 to 19, 2021 . Domestic and foreign experts ,famous manufacturers from laser, photonics and optical industries gather here to exchange the most advanced photonics science and technology , focusing on the development of China's photonics industry. During the exhibition, Infostone visited MRSI Systems' booth in Hall W2 2587, and interviewed Dr. Limin Zhou, Senior Director of Strategic Marketing of MRSI Systems.

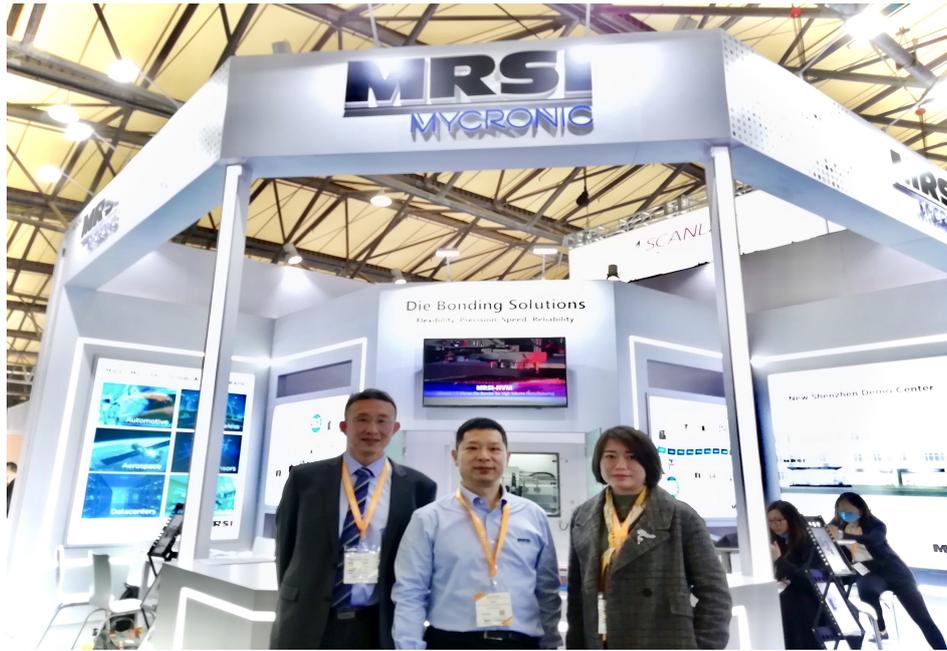


Figure 1 Dr. Zhou and the new employees in China at the Exhibition

Dr. Zhou introduced to Infostone that MRSI Systems continues to bring the most advanced 1.5 micron automatic die bonder with high-speed, high-precision, ultra- flexible, providing on-site demonstration for domestic device manufacturers as well. The MRSI-H series die bonder is the industry's proven solution for high-precision, high-volume manufacturing devices. The product is divided into four models to meet the needs of customers' different applications, including the full-function model MRSI-H-LD, MRSI-H-HPLD for high-power laser bonding, MRSI-H-LDMOS for microwave RF devices, and MRSI-H-TO for complex TO bonding.

By understanding, the most widely used in the photonics device industry is MRSI-HVM series die bonder @1.5 micron precision, which is tailored for the needs of high-volume and high-mix manufacturing solutions. The bonding precision of MRSI-H series

and MRSI-HVM series die bonders are very stable with the characteristic of high flexibility, and the stable precision can reach less than 3 microns in the post bonding, which can realize the production of multi-die and multi-process. At present, only MRSI-HVM Family and MRSI-H Family die bonders in the world can achieve mass production stably with high-speed under the accuracy of 3 micron bonding. For devices that requiring multi-die and high-density on eutectic process, MRSI provides a hot head heating solution. By adopting the special top heating design with high-speed and high-precision , the double reflow of adjacent die during the eutectic process can be effectively prevented.

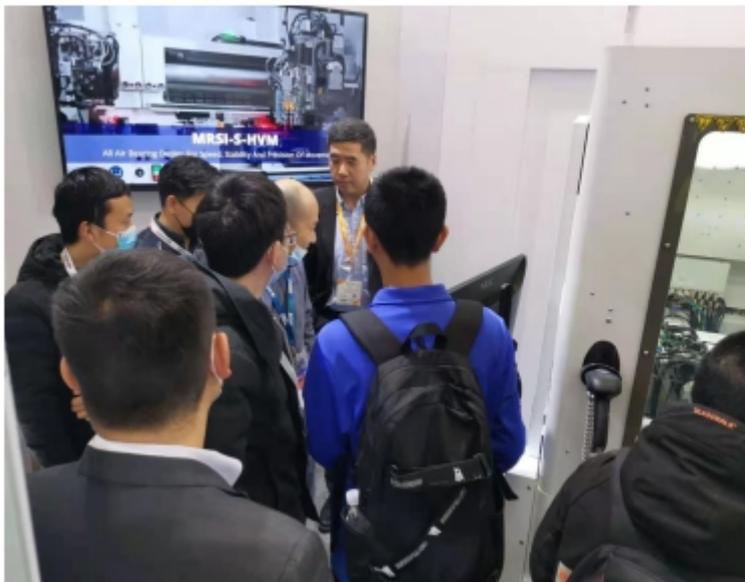




Figure. 2 Scene of audience at MRSI booth

At the show, MRSI also displayed the sub-micron die bonder which has the industry's highest standard of double precision design , MRSI-S-HVM is the world's first dual precision (0.5  $\mu\text{m}$  and 1.5  $\mu\text{m}$ ) mode sub-micron fully-automatic die bonder with industry-leading speed and ultra- flexibility. This die bonder supports wafer level bonding, achieving multi-die and multi-process operated in one machine, which is the best solution for wafer level bonding and high-speed, high-volume manufacturing of silicon photonics devices as well as microelectronic devices. As soon as the die bonder was launched in 2020, it has attracted widely attention in the industry. A large number of visitors showed strong interests and purchase intention in this die bonder at the Exhibition.

In the end of this interview, Dr. Zhou introduced that MRSI provides series of high- precision, high- speed and high- flexibility die bonding solutions ranging from 5 micron to 0.5 micron, which can be configured according to the requirements of different applications. The most important characteristic of MRSI die bonder is the stability which is regarded as the Holy grail that have MRSI always be in the leading position in the industry. At the same time, MRSI attaches great importance to the co-development with customers, in-depth understanding of customer needs, through continuous innovation to provide market value for customers.

With the development of 5G, data centers, and laser application markets, innovative, photonics devices are rapidly iterating. To meet the production needs of new devices, MRSI is always committed to developing the best innovative solutions. According to the introduction, in recent years, the performance of MRSI company in China maintains sustained and rapid growth. MRSI is very optimistic about the development of Chinese and Asian markets. As the company's business continues to grow, MRSI will improve the company's services in China in further step.

In 2021, MRSI will build a new China Product Demonstration Center in the Science and Technology Park of Nanshan District, Shenzhen, which will serve customers in China and Asia. At present the Demo center is being decorated intensely and expected to meet with everybody in April - May. The Demo center will be equipped with MRSI's advanced full-function die bonder MRSI-HVM-P and experienced application service experts to provide customers with the best MRSI product experience. In the

new year, MRSI will also increase the sales staff and application service engineers in China so as to respond to customer needs more quickly. To visit and learn more about MRSI Systems' die bonding solutions at MRSI's Shenzhen Demonstration Center, please contact Dr. Limin Zhou, Senior Director of Strategic Marketing, MRSI Systems, [limin.zhou@mycronic.com](mailto:limin.zhou@mycronic.com).